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Effect of metallic coating on the properties of copper-silicon carbide composites

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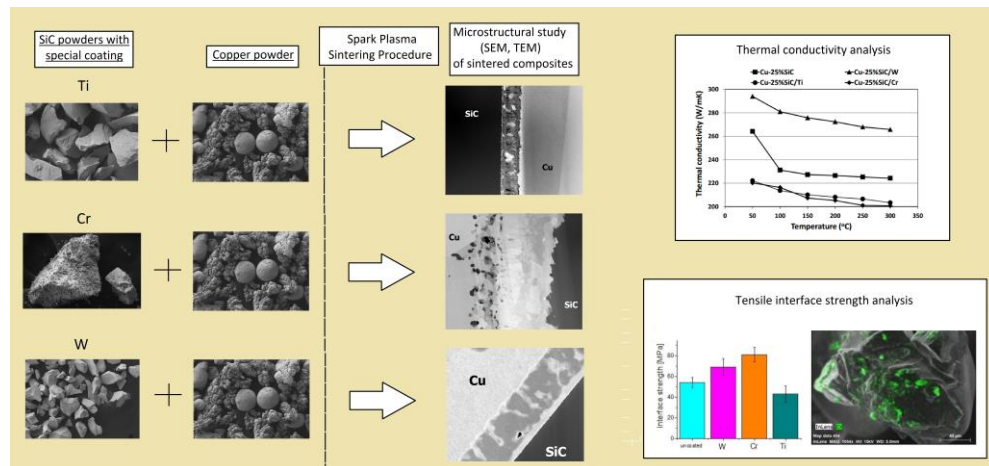
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Graphical abstract



Highlights

- Development of metallic deposition technique on silicon carbide particles
- Metallic layers limit the dissolution of silicon in copper matrix
- Morphology of layer has crucial importance for thermal conductivity of materials
- The type of material strongly influence on mechanical strength of interface
- Cu/SiC composites may be used as heat dissipation elements

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